	BILL OF MATERIALS						
TI Designs#	TIDA-00460						
Fitted	Description	Designator	Footprint	Manufacturer	PartNumber	Quantity	RoHS
ïtted	RES, 4.99, 1%, 0.1 W, 0603	R14	0603	Yageo America	RC0603FR-074R99L	1	Y
itted	RES,1M ohm, 5%, 0.063W, 0402	R3	0402	Yageo	CRCW04021M00JNED	1	Y
itted	LED, Green, SMD	D2	LED_0603	Wurth Elektronik eiSos	150060VS75000	1	Y
ïtted	LED, Super Red, SMD	D3	LED_0603	Wurth Elektronik eiSos	150060SS75000	1	Y
ïtted	RES, 0, 5%, 0.063 W, 0402	R12, R13	0402	Vishay-Dale	CRCW04020000Z0ED	2	Y
itted	RES, 1.0k ohm, 5%, 0.063W, 0402	R7, R8	0402	Vishay-Dale	CRCW04021K00JNED	2	Y
ïtted	RES, 27, 5%, 0.063 W, 0402	R2, R4	0402	Vishay-Dale	CRCW040227R0JNED	2	Y
ïtted	RES, 33 ohm, 5%, 0.1W, 0603	R5	0603	Vishay-Dale	CRCW060333R0JNEA	1	Y
itted	RES, 33k ohm, 5%, 0.063W, 0402	R9	0402	Vishay-Dale	CRCW040233K0JNED	1	Y
	1.8V High Resolution Inductance to Digital Converter,						
Fitted	DRC0010J ESD in 0402 Package with 10 pF Capacitance and 6 V	U5	DRC0010J	Texas Instruments	LDC1101DRC	1	Y
	Breakdown, 1 Channel, -40 to +125 degC, 2-pin X2SON						
Fitted	(DPY), Green (RoHS & no Sb/Br)	U3, U6	DPY0002A	Texas Instruments	TPD1E10B06DPYR	2	
	Low-Capacitance + / - 15 kV ESD-Protection Array for High-						
Fitted	Speed Data Interfaces, 2 Channels, -40 to +85 degC, 5-pin SOT (DRL), Green (RoHS & no Sb/Br)	U2	DRL0005A	Texas Instruments	TPD2E001DRLR	1	
	Micropower, 150mA Low-Dropout CMOS Voltage						
itted	Regulator, 5-pin SC-70, Pb-Free	U1	MAA05A	Texas Instruments	LP5951MG-3.3/NOPB	1	Y
itted	Mixed Signal MicroController, RGC0064B	U4	RGC0064B	Texas Instruments	MSP430F5528IRGC	1	Y
itted	CAP, CERM, 220nF, 10V, 10%, X7R, 0402	C18, C20	0402	TDK Corporation	C1005X7R1A224K050BB	2	Y
itted	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0402	C2, C7, C11, C25, C26, C27	0402	трк	C1005X7R1H104K050BB	6	Y
Fitted	CAP, CERM, 10uF, 10V, +/-20%, X5R, 0603	C23	0603	ток	C1608X5R1A106M	1	Y
Fitted	Inductor, Shielded, Ferrite, 10uH, 0.4A, 1.38 ohm, SMD	L1	2.0x0.95x1.6mm	TDK	VLS201610ET-100M	1	Y
Not Fitted	CAP, CERM, 330pF, 50V, +/-1%, C0G/NP0, 0603	C_TANK	0603	трк	C1608C0G1H331F080AA	0	Y
		<u></u>		Sullins Connector			1
Fitted	Header (shrouded), 100 mil, 7x2, Gold plated, TH	J5	7x2 Shrouded Header	Solutions	SBH11-PBPC-D07-ST-BK	1	Y
Fitted	Header, 100mil, 3x1, Tin plated, TH	J1, J7, J9	Header, 3 PIN, 100mil, Tin	Sullins Connector Solutions	PEC03SAAN	3	Y
lited		51, 57, 55	Receptacle, 2.54 mm, 2x1, R/A,	Sullins Connector	I LOUSSAAN		
itted	Receptacle, 2.54 mm, 2x1, Tin, R/A, SMT	Je	SMT	Solutions	PPTC021LGBN-RC	1	Y
itted	Connector, Receptacle, 100mil, 10x2, Gold plated, TH	J2, J4	10x2 Receptacle	Samtec	SSW-110-23-F-D	2	Y
itted	Header, 2.54 mm, 2x1, Tin, TH	J8, J10	Header, 2.54 mm, 2x1, TH	Samtec	TSW-102-07-T-S	2	Y
Fitted	RES, 0, 5%, 0.1 W, 0603	R10, R11	0603	Panasonic	ERJ-3GEY0R00V	2	Y
Fitted	RES, 1.40 k, 1%, 0.1 W, 0402	R1	0402	Panasonic	ERJ-2RKF1401X	1	Y
Fitted	RES, 100, 1%, 0.1 W, 0402	R15	0402	Panasonic	ERJ-2RKF1000X	1	Y
lot Fitted	Fiducial mark. There is nothing to buy or mount.	FID1, FID2, FID3	Fiducial	N/A	N/A	0	
Fitted	CAP, CERM, 18 pF, 50 V, +/- 5%, C0G/NP0, 0402	C13, C14	0402	MuRata	GRM1555C1H180JA01D	2	Y
itted	CAP, CERM, 18pF, 100V, +/-5%, C0G/NP0, 0603	C16, C17, C21, C22	0603	MuRata	GRM1885C2A180JA01D	4	Y
itted	CAP, CERM, 1uF, 10V, +/-10%, X5R, 0402	C10	0402	MuRata	GRM155R61A105KE15D	1	Y
itted	CAP, CERM, 4.7 μF, 16 V, +/- 10%, X7R, 0805	C6	0805	MuRata	GRM21BR71C475KA73L	1	Y
lot Fitted	CAP, CERM, 2200pF, 6.3V, +/-10%, X7R, 0402	C15	0402	MuRata	GRM155R70J222KA01D	0	Y
itted	Test Point, Miniature, Black, TH	TP9, TP10	Black Miniature Testpoint	Keystone	5001		Y
Fitted	Test Point, Miniature, Red, TH	TP3	Red Miniature Testpoint	Keystone	5000		Y
itted	Test Point, Miniature, White, TH	TP4, TP8	White Miniature Testpoint	Keystone	5002	-	Y
Fitted	CAP, CERM, 0.015 µF, 25 V, +/- 5%, ,NP0 0603	C12	0603	Kemet	C0603C153J3GACTU	1	Y
	CAD CEDM 0.47. E $40V_{12}/40V_{13}/270, 00000000000000000000000000000000000$		0000		C0003C13535CACTU		t.

Fitted	Crystal, 24.000MHz, 18pF, SMD	Y1	3.2x0.8x2.5mm	Abracon Corportation	ABM8-24.000MHZ-B2-T	1 \	Y
Fitted	Shunt, 100mil, Gold plated, Black	SH-J1, SH-J7, SH-J8, SH-J9, SH-J10	Shunt	3M	969102-0000-DA	5 א	Y

0603

0603

0402

SOD-523

SOD-123

Connector USB Mini B

2.9x2x3.9mm SMD

PCB Label 0.650"H x 0.200"W

C19

C1, C3

C5, C8

J3

D4

D1

LBL1

PCB1

S2

CAP, CERM, 0.47uF, 10V, +/-10%, X7R, 0603

CAP, CERM, 2.2uF, 10V, +/-10%, X5R, 0603

Diode, Schottky, 20 V, 0.2 A, SOD-523

Diode, Zener, 5.6V, 500mW, SOD-123

10,000 per roll

Printed Circuit Board

Switch, Push Button, SMD

CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0402

Connector, Receptacle, Micro-USB Type B, SMT

Thermal Transfer Printable Labels, 0.650" W x 0.200" H -

Fitted

Fitted

Fitted

Fitted

Fitted

Fitted

Fitted

Fitted

Fitted

1 Y

2 Y

2 Y

1 Y

1 Y

1 Y

1 Y

10

1 Y

C0603C474K8RACTU

C0603C225K8PACTU

500R07S100JV4T

SBR0220T5-7-F

MMSZ5232B-7-F

THT-14-423-10

TIDA-00460

SKRKAEE010

ZX62R-B-5P

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